




APPLICABLE STANDARD						
RATING	OPERATING TEMPERATURE RANGE	-40°C TO + 85°C (NOTE 1) 	STORAGE TEMPERATURE RANGE		-10°C TO + 60°C (NOTE 2)	
	OPERATING HUMIDITY RANGE	40% TO 80% (NOTE 3)	STORAGE HUMIDITY RANGE		40% TO 70% (NOTE 2)	
	VOLTAGE	AC 250V	UL · CSA	VOLTAGE	AC 30V	
	CURRENT	2A	RATING	CURRENT	2A	
SPECIFICATIONS						
ITEM	TEST METHOD		REQUIREMENTS		QT	AT
CONSTRUCTION						
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.		X	X
MARKING	CONFIRMED VISUALLY.				X	X
ELECTRIC CHARACTERISTICS						
CONTACT RESISTANCE	100mA (DC OR 1000 Hz).		30mΩ MAX.		X	—
INSULATION RESISTANCE	500V DC.		1000MΩ MIN.		X	—
VOLTAGE PROOF	650V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.		X	—
MECHANICAL CHARACTERISTICS						
MECHANICAL OPERATION	30TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: 30mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—
VIBRATION	FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—
SHOCK	490 m/s <sup>2</sup> DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—
ENVIRONMENTAL CHARACTERISTICS						
DAMP HEAT (STEADY STATE)	EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.		① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 500MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55→ 5 TO 35→+85→ 5 TO 35°C TIME 30→ 5MAX → 30→ 5MAX min UNDER 5 CYCLES.		① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 1000MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.		X	—
RESISTANCE TO SOLDERING HEAT	1)AUTOMATIC SOLDERING (FLOW) SOLDER TEMPERATURE : 260°C FOR IMMERSION,DURATION , 10 sec . 2)MANUAL SOLDERING SOLDERING IRON TEMPERATURE : 300°C SOLDERING TIME : 2 sec. NO STRENGTH ON CONTACT.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.		X	—
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 230°C FOR INSERTION DURATION, 3sec.		SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.		X	—
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE	
	1	DIS-H-008540	MI. SAKIMURA	HK. UMEHARA	14. 02. 26	
REMARKS				APPROVED	TY. OMA	05. 08. 11
NOTE1:INCLUDING THE TEMPERATURE RISE BY CURRENT				CHECKED	HK. UMEHARA	05. 08. 11
NOTE2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION.				DESIGNED	IO. DENPOUYA	05. 08. 11
NOTE3:NON-CONDENSING. Unless otherwise specified , refer to IEC 60512.				DRAWN	MK. MATSUO	05. 08. 09
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-162391-02	
	SPECIFICATION SHEET		PART NO.	DF11-*DP-2DSA (24)		
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL543		1/1